

August 2011

# **QRE1113, QRE1113GR Minature Reflective Object Sensor**

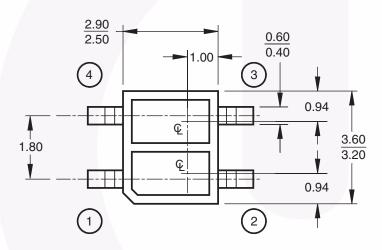
#### **Features**

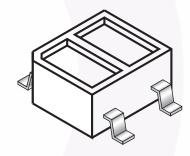
- Phototransistor output
- No contact surface sensing
- Miniature package
- Lead form style: Gull Wing

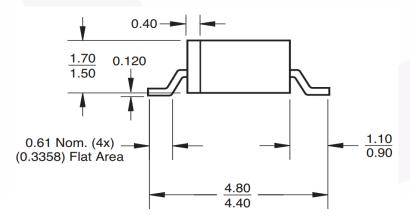
- Two leadform options: Through hole (QRE1113)
  - SMT gullwing (QRE1113GR)
- Two packaging options: Tube (QRE1113)

Tape and reel (QRE1113GR)

### **QRE1113GR Package Dimensions**



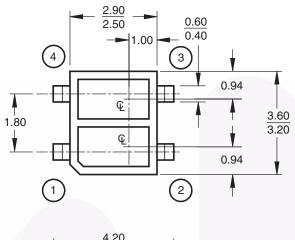


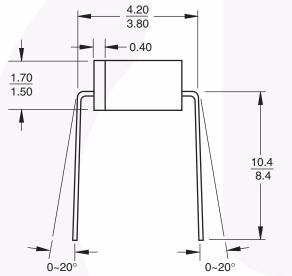


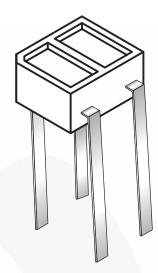
#### Notes:

- 1. Dimensions for all drawings are in millimeters.
- 2. Tolerance of ±0.15mm on all non-nominal dimensions

### **QRE1113 Package Dimensions**



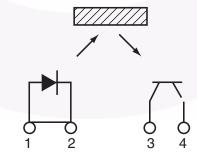




#### Notes:

- 1. Dimensions for all drawings are in millimeters.
- 2. Tolerance of ±0.15mm on all non-nominal dimensions

### **Schematic**



Pin 1: Anode Pin 2: Cathode Pin 3: Collector Pin 4: Emitter

### **Absolute Maximum Ratings** (T<sub>A</sub> = 25°C unless otherwise specified)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating	<b>Units</b> °C	
T <sub>OPR</sub>	Operating Temperature	-40 to +85		
T <sub>STG</sub>	Storage Temperature	-40 to +90	°C	
T <sub>SOL-I</sub>	Soldering Temperature (Iron) <sup>(2,3,4)</sup>	240 for 5 sec	°C	
T <sub>SOL-F</sub>	Soldering Temperature (Flow) <sup>(2,3)</sup>	260 for 10 sec	°C	
EMITTER	·			
I <sub>F</sub>	Continuous Forward Current	50	mA	
V <sub>R</sub>	Reverse Voltage	5	V	
I <sub>FP</sub>	Peak Forward Current <sup>(5)</sup>	1	А	
P <sub>D</sub>	Power Dissipation <sup>(1)</sup>	75	mW	
SENSOR	·			
V <sub>CEO</sub>	Collector-Emitter Voltage	30	V	
V <sub>ECO</sub>	Emitter-Collector Voltage	5	V	
I <sub>C</sub>	Collector Current	20	mA	
$P_{D}$	Power Dissipation <sup>(1)</sup>	50	mW	

### **Electrical/Optical Characteristics** (T<sub>A</sub> = 25°C unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
INPUT DIODE						
V <sub>F</sub>	Forward Voltage	I <sub>F</sub> = 20mA		1.2	1.6	V
I <sub>R</sub>	Reverse Leakage Current	$V_R = 5V$			10	μA
$\lambda_{PE}$	Peak Emission Wavelength	I <sub>F</sub> = 20mA		940		nm
OUTPUT TRANSISTOR						
I <sub>D</sub>	Collector-Emitter Dark Current	$I_F = 0$ mA, $V_{CE} = 20$ V			100	nA
COUPLED						
I <sub>C(ON)</sub>	On-State Collector Current	$I_F = 20 \text{mA}, V_{CE} = 5V^{(6)}$	0.10	0.40		mA
I <sub>CX</sub>	Cross-Talk Collector Current	$I_F = 20 \text{mA}, V_{CE} = 5V^{(7)}$			1	μΑ
V <sub>CE (SAT)</sub>	Saturation Voltage				0.3	V
t <sub>r</sub>	Rise Time	$V_{CC} = 5V, I_{C(ON)} = 100\mu A,$		20		μs
t <sub>f</sub>	Fall Time	$R_L = 1k\Omega$		20		

#### Notes:

- 1. Derate power dissipation linearly 1.00mW/°C above 25°C.
- 2. RMA flux is recommended.
- 3. Methanol or isopropyl alcohols are recommended as cleaning agents.
- 4. Soldering iron 1/16" (1.6mm) from housing.
- 5. Pulse conditions:  $tp = 100\mu s$ ; T = 10ms.
- 6. Measured using an aluminum alloy mirror at d = 1mm.
- 7. No reflective surface at close proximity.

### **Typical Performance Curves**

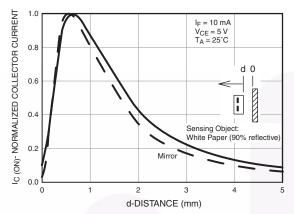
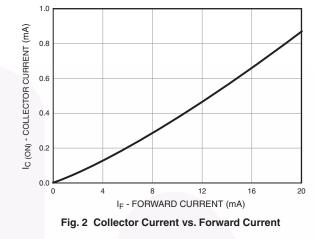


Fig. 1 Normalized Collector Current vs. Distance between device and reflector



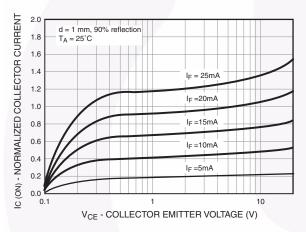


Fig. 3 Normalized Collector Current vs. Collector to Emitter Voltage

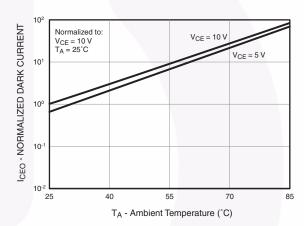


Fig. 4 Collector Emitter Dark Current (Normalized) vs. Ambient Temperature

### **Typical Performance Curves** (Continued)

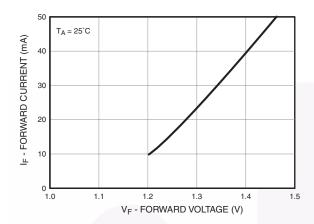


Fig. 6 Forward Current vs. Forward Voltage

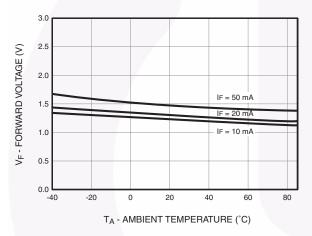


Fig. 8 Forward Voltage vs. Ambient Temperature

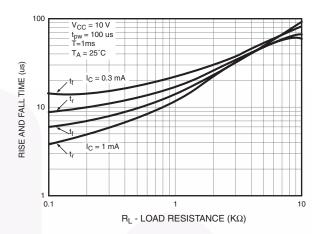


Fig. 7 Rise and Fall Time vs. Load Resistance

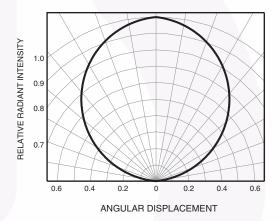
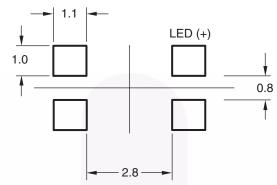


Fig. 8 Radiation Diagram

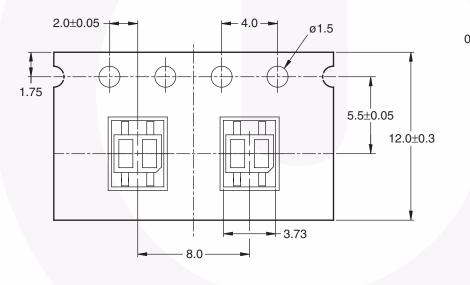
### Recommended Solder Screen Pattern for GR option (for reference only)

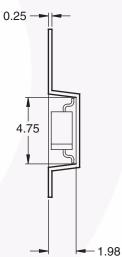


Dimensions in mm

## **Taping Dimensions for GR option**

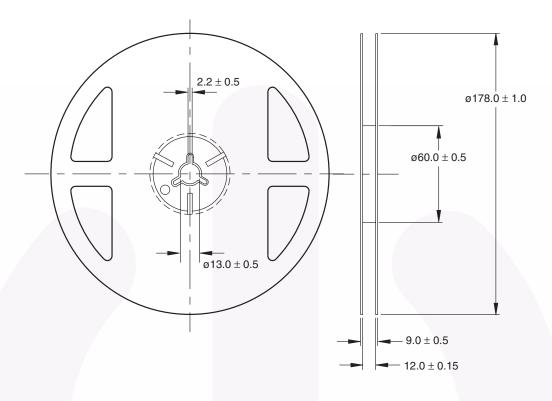
### Progressive Direction



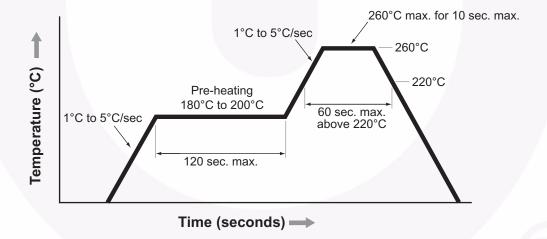


General tolerance ±0.1 Dimensions in mm

### **Reel Dimensions**



### **Reflow Profile**



Note: Reflow soldering should not be done more than twice.



#### **TRADEMARKS**

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

F-PFS™ AccuPower™ AX-CAP FRFET® Global Power Resource<sup>SM</sup> BitSiC™ Build it Now™ GreenBridge™

CorePLUS™ Green FPS™ Green FPS™ e-Series™ CorePOWER™ Gmax™

 $CROSSVOLT^{\text{\tiny TM}}$ CTL™ GTO™ IntelliMAX™ Current Transfer Logic™ DEUXPEED<sup>®</sup> ISOPLANAR™

Dual Cool™ Making Small Speakers Sound Louder and Better™

MicroPak™

MicroPak2™

EcoSPARK® EfficientMax™ MegaBuck™ MICROCOUPLER™ **ESBC™ F**® MicroFET™

Fairchild® Fairchild Semiconductor® FACT Quiet Series™ FACT

MillerDrive™ MotionMax™ mWSaver™ FAST® OptoHiT™ FastvCore™ OPTOLOGIC® FFTBench™ OPTOPLANAR® PowerTrench® PowerXS<sup>TI</sup>

Programmable Active Droop™

**QFET** QS<sup>TM</sup> Quiet Series™ RapidConfigure™

Saving our world, 1mW/W/kW at a time™

SignalWise™ SmartMax™ SMART START™

Solutions for Your Success™

SPM® STEALTH™ SuperFET® SuperSOT™-3 SuperSOT™-6 SuperSOT™-8 SupreMOS® SvncFET™

Sync-Lock™ SYSTEM SYSTEM TinyBoost™

TinyBuck™ TinyCalc™ TinyLogic® TINYOPTO™ TinyPower™ TinyPWM™ TinyWire™ TranSiC™ TriFault Detect™ TRUECURRENT®\* սSerDes™

UHC' Ultra FRFET™ UniFET™  $VCX^{TM}$ VisualMax™ VoltagePlus™ XSTM

#### DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

#### LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

- 1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- 2. A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

#### **ANTI-COUNTERFEITING POLICY**

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com,

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

#### PRODUCT STATUS DEFINITIONS

#### **Definition of Terms**

Datasheet Identification	Product Status	Definition		
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may chain any manner without notice.		
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.		
No Identification Needed Full Production		Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.		
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.		

Rev. 164

<sup>\*</sup> Trademarks of System General Corporation, used under license by Fairchild Semiconductor.